



**MICROPOSIT™ EBR-10 A**  
**EDGE BEAD REMOVER**  
 For Post-etch Applications

**Regional Product Availability**

- North America
- Europe, Middle East and Africa
- Latin America
- Asia-Pacific

**Description**

MICROPOSIT EBR-10 A Edge Bead Remover is engineered to eliminate the photoresist edge bead that occurs during typical spin coat wafer processing.

Removing the edge bead immediately after photoresist coating reduces particulate associated defects caused by subsequent wafer processing.

The MICROPOSIT EBR-10 A Edge Bead Remover is a toxicologically-safer alternative to the ethylene glycol-derived ether acetates. It is compatible with all MICROPOSIT and MEGAPOSIT™ Photoresists. It offers efficient and expedient removal of photoresist edge bead. It has an improvement of yield through defect reduction. MICROPOSIT EBR-10 A Edge Bead Remover has a low metal-ion content.

**Product Data**

Color: Clear  
 Flash Point: 46°C (115°F)  
 Boling Point: 146°C (295°F)  
 Water Solubility: Insoluble

Consult material safety data sheet (MSDS) for a complete listing of physical properties, handling, storage and disposal.

**Instructions for Use**

MICROPOSIT EBR-10 A Edge Bead Remover is a ready-to-use product.

**Typical Processing Conditions**

Edge Bead Removal (EBR) is an equipment-dependent process. Exact application programs (spin speeds and times) depend on wafer size, nozzle placement, spray pressure, amount of edge bead, exhaust flow, wafer bevel and resist solubility. Uniform and repeatable EBR using a TEL™ MARK 8 has been attained with the process steps shown.

**Process Steps**

- 1) Decelerate spin speed to 1,500 rpm and stabilize spin speed for 2 seconds directly after photoresist application and final spin to nominal thickness.
- 2) Start top side EBR dispense at 1,500 rpm after 1 sec.
- 3) Turn backside EBR dispense on (3 psi) while spinning at 1,500 rpm while maintaining top dispense.
- 4) Turn backside EBR dispense off after 7 seconds.
- 5) After additional 1 sec. turn off top EBR dispense.
- 6) Spin at 1,500 rpm for 11 seconds.
- 7) End process.

Compatible  
Materials

Stainless steel  
Glass  
Ceramic  
Polypropylene  
High-density polyethylene  
Polytetrafluoroethylene

## Handling Precautions

Before using this product, associated generic chemicals or the analytical reagents required for its control, consult the supplier's Material Safety Data Sheet (MSDS)/Safety Data Sheet (SDS) for details on material hazards, recommended handling precautions and product storage.

**CAUTION!** Keep combustible and/or flammable products and their vapors away from heat, sparks, flames and other sources of ignition including static discharge. Processing or operating at temperatures near or above product flashpoint may pose a fire hazard. Use appropriate grounding and bonding techniques to manage static discharge hazards.

**CAUTION!** Failure to maintain proper volume level when using immersion heaters can expose tank and solution to excessive heat resulting in a possible combustion hazard, particularly when plastic tanks are used.

## Storage

Store products in tightly closed original containers at temperatures recommended on the product label.

## Disposal Considerations

Dispose in accordance with all local, state (provincial) and federal regulations. Empty containers may contain hazardous residues. This material and its container must be disposed in a safe and legal manner.

It is the user's responsibility to verify that treatment and disposal procedures comply with local, state (provincial) and federal regulations. Contact your Dow Electronic Materials Technical Representative for more information.

## Product Stewardship

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